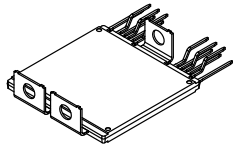


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



AHPM15-CDA MODULE

CASE MODHG

ISSUE B

DATE 22 SEP 2021

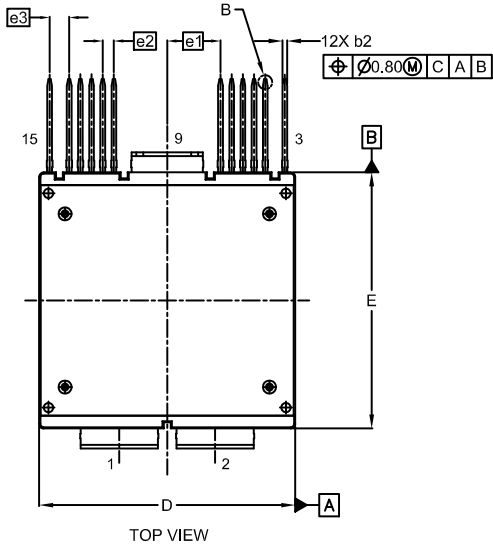


END VIEW

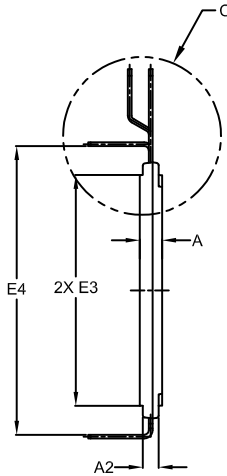
$\oplus \varnothing 0.60 \text{ (M) C A B}$

NOTES:

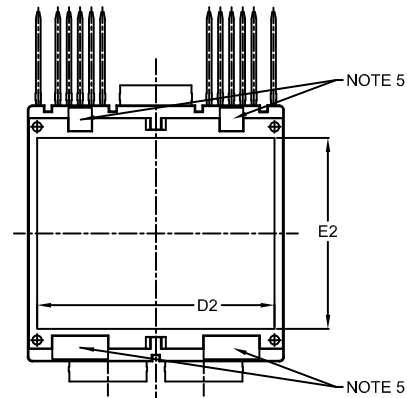
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E DO NOT INCLUDE MOLD PROTRUSIONS
4. DIMENSIONS b,b1,b2 DO NOT INCLUDE DAMBAR REMAIN.
5. MARKING AREA.



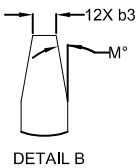
TOP VIEW



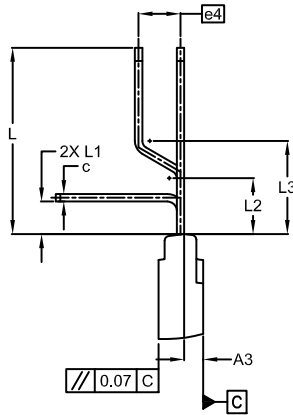
SIDE VIEW



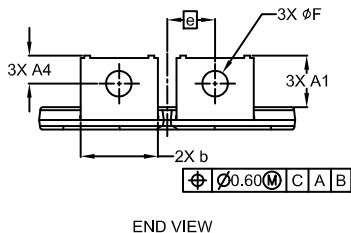
BOTTOM VIEW



DETAIL B



DETAIL C
SCALE N/A



END VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.60	4.80	5.00
A1	10.75	11.05	11.35
A2	3.20	3.40	3.60
A3	1.70	2.05	2.40
A4	5.70	6.00	6.30
b	16.50	16.60	16.70
b1	15.20	15.30	15.40
b2	0.90	1.00	1.10
b3	0.50 REF		
c	0.70	0.80	0.90
D	54.80	55.00	55.20
D2	50.40	51.00	51.60

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E	54.80	55.00	55.20
E2	40.40	41.00	41.60
E3	49.40	49.60	49.80
E4	61.50	62.00	62.50
e	10.00	10.30	10.60
e1	11.15	11.45	11.75
e2	2.40 BSC		
e3	4.20 BSC		
e4	4.20	4.50	4.80
F	5.40	5.50	5.60
L	19.60	20.00	20.40
L1	3.10	3.50	3.90
L2	6.00 REF		
L3	10.00 REF		
M	10° REF		

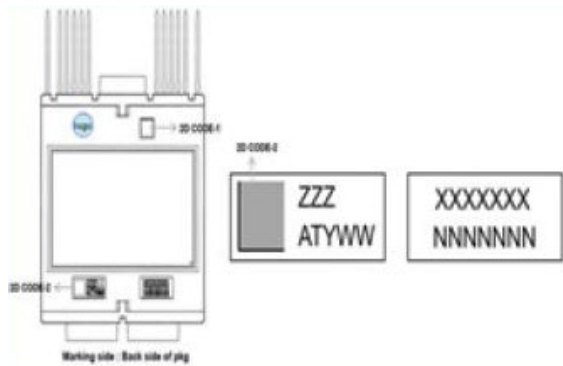
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DESCRIPTION:	AHPM15-CDA MODULE	PAGE 1 OF 2

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AHPM15-CDA MODULE
CASE MODHG
ISSUE A

DATE 22 SEP 2021


GENERIC
MARKING DIAGRAM*



ZZZ = Assembly Lot Code
 AT = Assembly & Test Location
 Y = Year
 WW = Work Week
 NNNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	AHPM15-CDA MODULE	PAGE 2 OF 2

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